

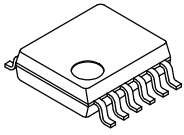
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®

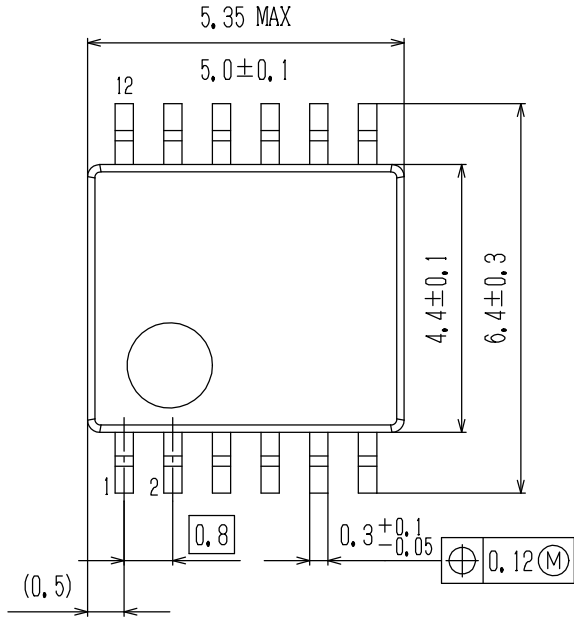


**SOIC12 W / MFP12S (225 mil)**  
**CASE 751BY**  
**ISSUE O**

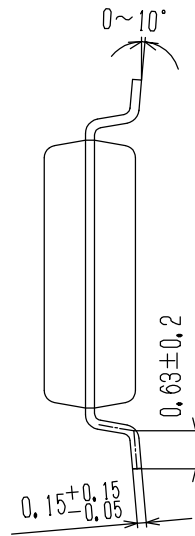
DATE 29 FEB 2012



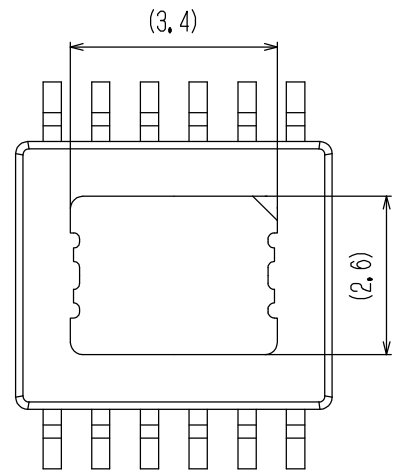
TOP VIEW



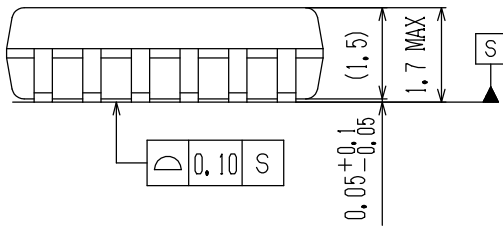
SIDE VIEW



BOTTOM VIEW



SIDE VIEW



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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>SOIC12 W / MFP12S (225 MIL)</b>	<b>PAGE 1 OF 2</b>

